



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF: JAMES L. VOELZ

APPLICATION No.: 10/687,096

FILED: OCTOBER 15, 2003

FOR: **METHODS FOR WAFER-LEVEL
PACKAGING OF MICROELECTRONIC
DEVICES AND MICROELECTRONIC
DEVICES FORMED BY SUCH METHODS**

EXAMINER: SARA W. CRANE

ART UNIT: 2811

CONF. No: 7233

Amendment Under 37 C.F.R. § 1.111

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

The present communication responds to the Office Action dated December 15, 2005 in the above-identified application. Please amend the application as follows:

Amendments to the Claims are reflected in the listing of claims beginning on page 2.

Remarks begin on page 9 of this paper.